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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

U.S. Patent Application of:
Cheah et al.

Application No.: 10/068,523

Group Art Unit: 2811

Filed: February 5, 2002

Examiner: To Be Assigned

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Attorney Docket No.: 9818-066-999

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Pursuant to 37 C.F.R. § 1.56, Applicants submit an Information Disclosure Statement and a list of cited references for the Examiner's review and consideration. Copies of each of the cited references are provided. The Examiner is respectfully requested to consider each of these references.

This Information Disclosure Statement is filed under 37 C.F.R. § 1.97(b) before the mailing of the first Office Action on the merits. Thus, in accordance with 37 C.F.R. § 1.97(b), it is believed that no fee is required. Should one be required, however, please charge it to Pennie & Edmond's Deposit Account No. 16-1150

Respectfully submitted,

Date May 3, 2002

A handwritten signature of Francis E. Morris.

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Enclosures